

Amendment to the Specification

Please replace Table 2 on page 22 with the following table.

REFLECTANCE SHEET

TABLE 2

	Comparative Example										
	3	3	3	4	5	4	7	9	9	10	11
Phenol biphenylaralkyl type epoxy resin	7.4	8.4		7.4	7.5	7.6	7.35	7.35	7.4	7.35	7.35
Biphenyl type epoxy resin			6.9								
Cresol novolac type epoxy resin											
Phenol biphenylaralkyl resin	5.5			5.5	5.52	5.55	5.5	5.5	5.5	5.5	5.5
Phenocaralkyl resin			6.0								
Phenol novolac resin		3.5									
Spherical fused silica	85.0	85.0	85.0	85.0	85.0	85.0	85.0	85.0	85.0	85.0	85.0
γ-glycidypropyltrimethoxysilane	0.4	0.4	0.4		0.4		0.4	0.4	0.4	0.4	0.4
γ-allyloxypropyltrimethoxysilane				0.4							
Triphenylphosphine	0.2	0.15	0.15	0.2	0.06	0.2	0.2	0.2			
DBU									0.2		
Curing accelerator of formula C7										0.25	
Curing accelerator of formula C8											0.25
2,3-Dihydroxynaphthalene		0.05	0.05			0.05					
1,2-Dihydroxynaphthalene											
Catechol											
Pyrogallol											
1,6-Dihydroxynaphthalene							0.05				
Resorcinol								0.05			
Cameras wax	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2
Carbon black	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3
Spiral flow (cm)	80	76	71	62	114	76	78	81	68	89	77
Curing torque ratio (%)	55	67	70	62	7	65	65	64	57	55	59
Solder resistance-cracking	4	2	chip	3		9	5	4	4	2	3
Internal crack	0	10	exposure	6	Poor	0	0	0	0	0	0
Fire retardancy	V-0	V-1	HB	V-0	Releasing	V-0	V-0	V-0	V-0	V-0	V-0